300mm Fully-Automatic BG Tape Laminator

**RAD-3510F/12**

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High precision fully-automatic BG Tape laminator. Wafer handling with non-contact alignment, tape lamination by TTC* technology and tape cutting with a multi-joint robot mechanism.

*TTC (Tape Tension Control) System: The TTC is a cutting-edge system, in which a microcomputer controls tape tension. It enables the tape to be laminated according to the tape type and back-end processing conditions. On the fully-automatic type, tape application torque and torque curve can be set and registered with the equipment's touch screen.

**Facility**

- **Power Supply**
  - Voltage: AC200-230V ±10% (AC190-253V)
  - Frequency: 50/60Hz
  - Phase: single phase
  - Power consumption: 1.0kW

- **Air Supply**
  - Air pressure: 0.5-0.8MPa
  - Air consumption: >150L/min (ANR)

- **Vacuum Supply**
  - Vacuum pressure: >-80kPa

**Applicable Wafer Size**

- 200mm, 300mm
  
  Please inquire about options for compatibility with specific wafer sizes.

**Size**

- **Width**: 1,350mm
- **Depth**: 1,700mm
- **Height**: 1,800mm

(excluding the signal tower)

**Weight**

- 1,500kg

**UPH**

- 60 wafers/hour

The above processing capacity is based on following conditions:

- **Wafer**: 300mm diameter non-polished mirror wafer
- **Back grinding tape**: P-1600B from LINTEC

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**Outline**

- **Options**
  - Host Communication Function (Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
  - Double Cassette Loading
  - Wafer Box Loading
  - Wafer ID Reader

- **Suitable Tapes**
  - BG Tape: Adwill E series, P series

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**External View**

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**Contact:**

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